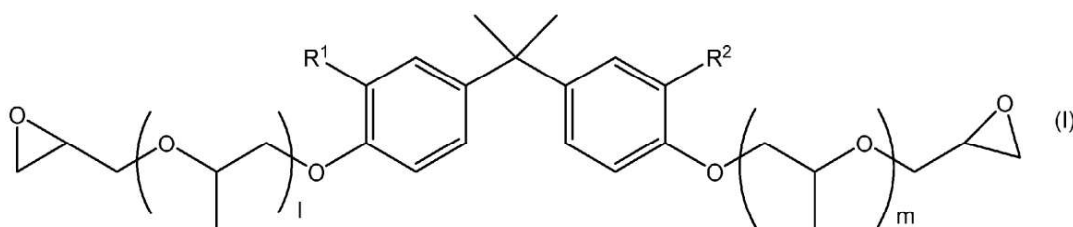


ABSTRACT

An adhesive tape for semiconductor, including: a film-like adhesive; and a pressure-sensitive adhesive tape laminated to the film-like adhesive, wherein the film-like adhesive contains an epoxy resin and a curing agent, the epoxy resin includes an epoxy resin that is liquid at 25 °C, and the epoxy resin that is liquid at 25 °C includes a compound represented by the following formula (I).

[Chem. 1]



[In formula (I), R¹ and R² each independently represent a hydrogen atom or a glycidyl group, and l and m each represent an integer of 0 or more; provided that when both R¹ and R² are hydrogen atoms, at least one of l and m is 1 or more.]

No Suitable Figure.